Recommended Operating Conditions at $Tc = 25 ^{\circ} C$

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage range	VM		9.0 to 32.0	V
Logic input voltage range	VIN		0 to 5.0	V
VCC input voltage range	Vcc		0 to 5.0	V
VREF input voltage range	VREF		0 to 3.0	V
Output current1	lo1	1-2 Phase-ex, Tc ≤ 90°C	3.0	Α
Output current2	lo2	1-2 Phase-ex, Tc=105°C	2.5	Α
Output current3	lo3	2 Phase-ex, Tc=105°C	1.8	Α

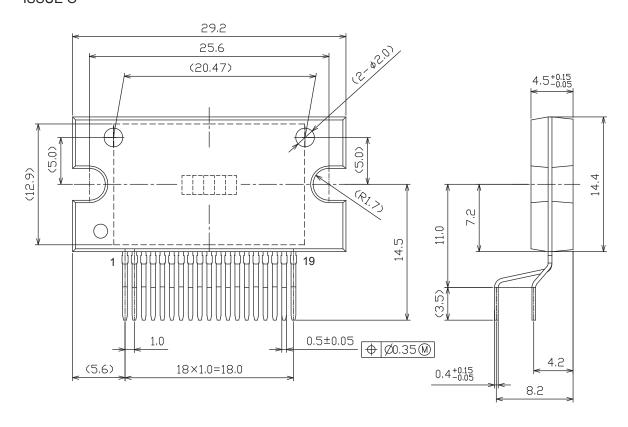
Electrical Characteristics at Tc = 25°C, $V_{CC} = 5V$

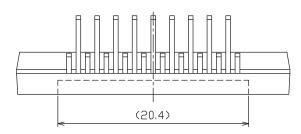
Darameter	Symbol	Conditions		Unit		
Parameter	Symbol	Conditions	min	typ	max	Unit
Standby mode current drain	IMstn	VCC="L"		70	100	μA
Current drain	IM	VCC="H", ENABLE="H" No Load		3.3	4.6	mA
Thermal shutdown temperature	TSD	Design guarantee	150	180	210	°C
Thermal hysteresis width	ΔTSD	Design guarantee		40		°C
	linL1	VIN=0.8V	3	8	15	μA
Logic pin input current	linH1	VIN=5V	30	50	70	μA
VCC pin input current	VCC	15pin=5V	51	83	115	μΑ
Logic input high-level voltage	Vinh	Pins 2,3,16,17,18,19	2.0			V
Logic input low-level voltage	Vinl	Pins 2,3,16,17,18,19			0.8	V
FDT pin high-level voltage	Vfdth	Pin 6	3.5			V
FDT pin middle-level voltage	Vfdtm	Pin 6	1.1		3.1	V
FDT pin low-level voltage	Vfdtl	Pin 6			0.8	V
Chopping frequency	Fch	C1=100pF	58	83	108	kHz
Chopping frequency	losc1			10		μA
Chopping oscillator circuit	Vtup1			1		V
threshold voltage	Vtdown1			0.5		V
VREF pin input voltage	Iref	VREF=1.5V, CLK=10kHz	-0.5			μA
DOWN output residual voltage	VolDO	Idown=1mA, CLK=Low		40		mV
Hold current switching frequency	Falert			1.6		Hz
Blanking time	Tb1			1		μs
Output block						
-	Ronu	I _O =2.0A, high-side ON resistance		0.30	0.42	Ω
Output on-resistance	Rond	I _O =2.0A, low-side ON resistance		0.25	0.35	Ω
Output leakage current	Ioleak	VM=36V			50	μA
Diode forward voltage	VD	ID=-2.0A		1.1	1.4	V
Current setting reference voltage	VRF	VREF=1.5V, Current ratio 100%		300		mV
Output short-circuit protection I	olock					
Timer latch time	Tscp			256		μs

Package Dimensions

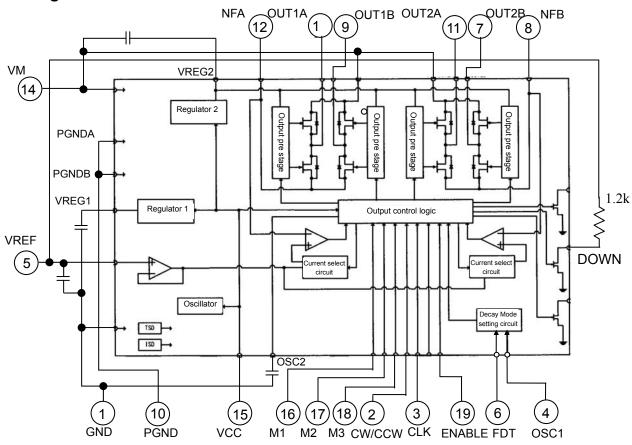
unit: mm

SIP19 29.2x14.4 CASE 127CF ISSUE O

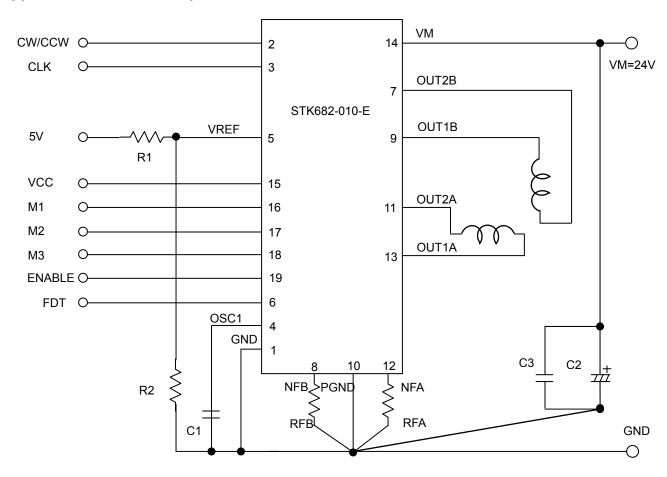




Block diagram



Application Circuit Example



Pin Functions

	1								
Pin No.	Pin symbol	Pin Functions							
1	GND	Circuit GND							
2	CW/CCW	Forward / Reverse signal input							
3	CLK	Clock pulse signal input							
4	OSC1	Chopping frequency setting capacitor connection							
5	VREF	Constant-current control reference voltage input							
6	FDT	Decay mode select voltage input							
7	OUT2B	B phase OUTB output							
8	NFB	B phase current sense resistance connection							
9	OUT1B	B phase OUTA output							
10	PGND	Power GND							
11	OUT2A	A phase OUTB output							
12	NFA	A phase current sense resistance connection							
13	OUT1A	A phase OUTA output							
14	VM	Motor supply connection							
15	VCC	Chip enable input							
16	M1								
17	M2	Excitation-mode switching pin							
18	M3								
19	ENABLE	Output enable signal input							

Equivalent circuit diagram

	ent circuit dia	
Pin No.	Pin type	Equivalent Circuit Diagram
3 2 19 18 17 16	CLK CW/CCW ENABLE M3 M2 M1	VREGIO 10KQ 100KQ VREGIO 10KQ
19	VOO	Internal reset Input pin 1 LIF SEARCH SEARC
13 10 14 12 11 9 8 7	OUT1A PGND VM NFA OUT2A OUT1B NFB OUT2B	
5	VREF	S DOWN
4	OSC1	CINITO (A)
6	FDT	72kΩ 23kΩ 9kΩ 6ND

Description of functions

(1) Excitation setting method

Set the excitation setting as shown in the following table by setting M1 pin, M2 pin and M3 pin

	Input signal			Initial position						
M3	M2	M1	MODE (Excitation)	A phase						
				current	B phase current					
L	L	L	2 Phase	100%	-100%					
L	L	Н	1-2 Phase	100%	0%					
L	Н	L	W1-2 Phase	100%	0%					
L	Н	Н	2W1-2 Phase	100%	0%					
Н	L	Ш	4W1-2 Phase	100%	0%					
Н	L	Η	8W1-2 Phase	100%	0%					
Н	Н	Ш	16W1-2 Phase	100%	0%					
Н	Н	Н	32W1-2 Phase	100%	0%					

The initial position is also the default state at start-up and excitation position at counter-reset in each excitation mode

(2) Output current setting

Output current is set as shown below by the VREF pin (applied voltage) and a resistance value between NFA (B) pin and GND.

IOUT = (VREF / 5) / NFA (B) resistance

(Example) When VREF=1.5V and NFA (B) resistance is 0.3 Ω , the setting current is shown below. IOUT = (1.5 V / 5) / 0.3 Ω = 1.0 A

(3) Chip enable terminal/ VCC function

When Chip enable terminal/ V_{CC} pin is at low levels, the IC enters stand-by mode, all logic is reset and output is turned OFF.

When Chip enable terminal/ V_{CC} pin is at high levels, the stand-by mode is released

(4) Step pin function

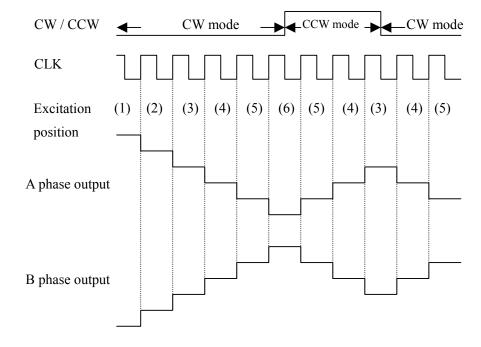
CLK pin step signal input allows advancing excitation step

Inp	out	Operation
VCC	CLK	
L	*	Stand-by mode
Н		Excitation step feed
Н		Excitation step hold

^{*} The setting value above is a 100% output current in each excitation mode.

(5) Forward / reverse switching function

CW/CCW	Operation
L	CW
Н	CCW

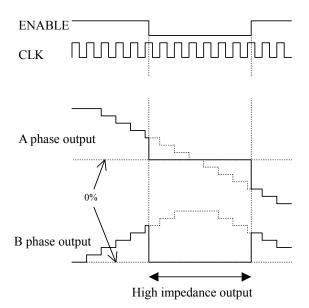


The internal D/A converter proceeds by a bit on the rising edge of the step signal input to the CLK pin. In addition, CW and CCW mode are switched by CW and CCW pin setting.

In CW mode, the B phase current is delayed by 90° relative to the A phase current. In CCW mode, the B phase current is advanced by 90° relative to the A phase current.

(6) Output enable function

When the ENABLE pin is set Low, the output is forced OFF and goes to high impedance. However, the internal logic circuits are operating, so the excitation position proceeds when the CLK is input. Therefore, when ENABLE pin is returned to High, the output level conforms to the excitation position proceeded by the CLK input.



(7) DECAY mode

The DECAY mode of the output current becomes only MIXED DECAY.

FDT voltage	DECAY method
3.5V to	SLOW DECAY
1.1V to 3.1V or OPEN	MIXED DECAY
to 0.8V	FAST DECAY

(8) Chopping frequency setting function

Chopping frequency is set as shown below by a capacitor between OSC1 pin and GND.

Fch =
$$1 / (C1+20pF / 10\times10^{-6})$$
 (Hz)

(Example) When Cosc1=100pF, the chopping frequency is shown below.

Fch =
$$1/((20+100)\times10^{-12}/10\times10^{-6})$$
 (Hz) = 83.3 (kHz)

Note

• The 20pF is a stray capacitance which is involved by the package of STK682-010-E.

(9) Output short-circuit protection circuit

Build-in output short-circuit protection circuit makes output to enter in stand-by mode. This function prevents the IC from damaging when the output shorts circuit by a voltage short or a ground short, etc. When output short state is detected, short-circuit detection circuit starts the operating and output is once turned OFF. After the timer latch time (typ: 256µs), output is turned ON again. Still the output is at short state, the output is turned OFF and fixed in stand-by mode.

When output is fixed in stand-by mode by output short protection circuit, output is released the latch by setting Chip enable terminal/ V_{CC} ="L"

(10) Internal DOWN pin

The DOWN pin is an open drain connection.

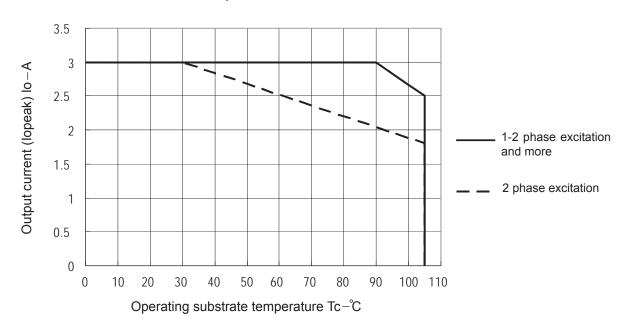
This pin is turned ON when no rising edge of CLK between the input signals while a period determined by a capacitor between OSC2 and GND, and outputs at low levels.

The DOWN pin output in once turned ON, is turned OFF at the next rising edge of CLK.

Holding current switching time (0.6sectyp) is set by an internal capacitor between OSC2 pin and GND.

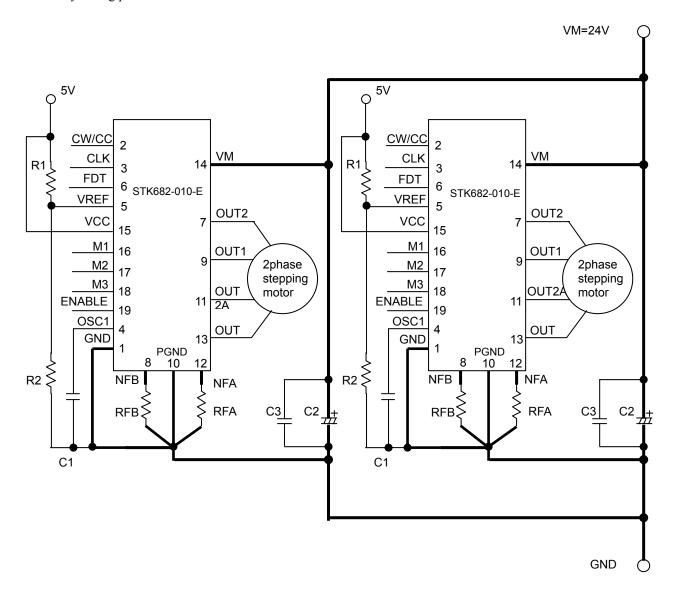
(11) Output current tolerance

STK682-010-E Output current tolerance lo-Tc

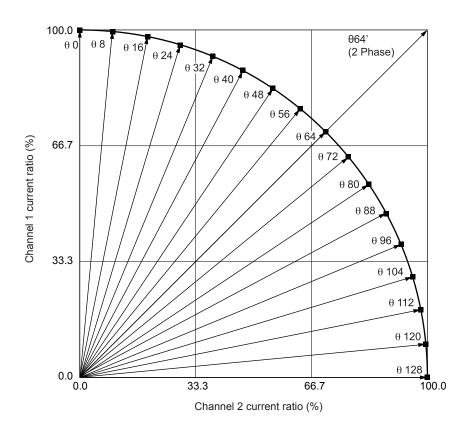


(12) When mounting multiple drivers on a single PC board

When mounting multiple drivers on a single PC board, the GND design should mount a VCC decoupling capacitor, C2 and C3, for each driver to stabilize the GND potential of the other drivers. The key wiring points are as follows.



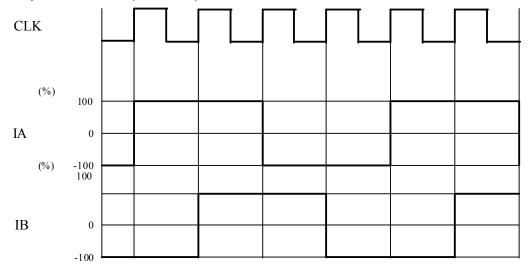
(13) Output current vector locus (1 step normalized 90°)



(14) Current setting ratio in each excitation mode

	32W1-2 p	haaa/0/1	1011111 0	ahaaa(0/)	014/4 2 -	-b(0/)	410/4 2 -	ahaaa/0/\	200/4 2 -	-h(0/)	W/4 2 m	haaa/8/ \	1 2 ph	200(9/)	2 pha	00(9/)		DOLAY 4 O	nhane/0/	1018/1 0	-b/0/	8W1-2 p	haaa/0/)	41M/4 2 -	haaa/0/)	200/4 2	ahaaa/8/ \	W4 2 -	heee(%/)	1.2 ph	000(9/)	2 pho	no(9/)
STEP																	STEP					Ach											
																BCII					BUII	ACII	BCII	ACII	BUII	ACII	BCII	ACII	BCII	ACII	BCII	ACII	BUII
θ0	100	0		U	100	0	100	U	100	U	100	0	100	0			065	70															$ldsymbol{\sqcup}$
θ1	100	1															966	69			72												
θ2	100	2	100	2													θ67	68															
θ3	100	4															θ68	67	74	67	74	67	74										
θ4	100	5	100	- 5	100	5											θ69	66	75														
θ5	100	6															970	65			76								1			-	-
θ6	100	7		7													070	64			- , ,	-						 	 	—		-	\vdash
																						- 00		- 00			-	_	_	_		-	\vdash
θ7	100	9															θ72	63			77	63	77	63	77								-
θ8	100	10	100	10	100	10	100	10									0 73	62															
θ9	99	11															θ74	62	79	62	79											. !	i I
θ10	99	12	99	12													θ75	61	80														
θ11	99	13		<u> </u>													076	60			80	60	80						t			-	-
θ12	99	15		15	99	15											077	59			- 00	- 00	- 00						1	_	-	-	-
			99	15	99	15						_	_			_					- 00	-						 	<u> </u>	<u> </u>		-	\vdash
θ13	99	16															978	58			82												-
θ14	99	17		17													0 79	57															
θ15	98	18															θ80	56	83	56	83	56	83	56	83	56	83						
θ16	98	20		20	98	20	98	20	98	20							θ81	55														\neg	-
017	98	21	Ť	–	<u> </u>	Ť				_ <u>_</u> _							082	53			84	-					1		1			\neg	\vdash
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θ19	97	23															θ84	51			86	51	86				<u> </u>		L				ш
θ20	97	24	97	24	97	24	Щ_	Щ_				L	L	L	L	L	θ85	50			∟_¯			L		L	Щ_	∟_¯	L	┗_		1]
θ21	97	25															θ86	49			87												\Box
θ22	96	27	96	27								i	i	1			087	48				-							1			-	-
θ23	96	28	- 55	 -	\vdash		\vdash	\vdash			\vdash	—	—				088	47			88	47	88	47	88	_	\vdash	\vdash	 	\vdash	\vdash	-	\vdash
			-00	200	-00	22	00	200		\vdash	\vdash	-	-								00	7/	00	4/	00	-	-	-	├	-		\rightarrow	\vdash
θ24	96	29	96	29	96	29	96	29									089	46															-
θ25	95	30															090	45			89												
θ26	95	31	95	31													θ91	44	90														
θ27	95	33															θ92	43	90	43	90	43	90										
θ28	94	34	94	34	94	34											093	42			- 00		- 00									-	-
020		25	94	37	37	77														44	04	-						.	-	_		-	\vdash
θ29 θ30	94	35 36															094	41	91	41	91												\vdash
030	93	36	93	36													θ95	39															
θ31	93	37															θ96	38	92	38	92	38	92	38	92	38	92	38	92			. !	1 1
θ32	92	38	92	38	92	38	92	38	92	38	92	38					θ97	37	93														\Box
θ33	92	39															098	36			93											-	-
θ34	91	41	91	41													099	35			- 50	-						-	1	—		-	-
		41	91	41																	~4	- ~ 4	- 0.4							_		-	-
θ35	91	42															θ100	34			94	34	94										
θ36	90	43	99	43	90	43											θ101	33															
θ37	90	44															θ102	31	95	31	95												
θ38	89	45	89	45													θ103	30	95														
θ39	89	46															0104	29	96	29	96	29	96	29	96				1				
040	88		00	47	00	47	00	47										28	96	23	30	23	30	23	30		-	 	-	—		-	-
		47	88	47	88	47	88	47									0105															_	\vdash
θ41	88	48															θ106	27			96												
θ42	87	49	87	49													θ107	25	97														
θ43	86	50															θ108	24	97	24	97	24	97										
θ44	86	51	86	51	86	51											0109	23	97													\neg	\Box
045	85	52		– ∸	<u></u>	<u> </u>						_	_				0110	22	98	22	98								_		-	\neg	-
			0.4	E2			1	1	-	\vdash	\vdash	\vdash	\vdash	-			θ111				- 30	\vdash	-	_		_	1	\vdash	1		\vdash	\rightarrow	\vdash
θ46	84	53	84	53		_	-	-	_	\vdash	\vdash	⊢—	⊢—	—				21				L	- 00				000	_	—	Ь—	\vdash		\vdash
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θ48	83	56	83	56	83	56	83	56	83	56							θ113	18]	
049	82	57															θ114	17	99	17	99												
θ50	82	58	82	58													θ115	16			m	-										=	-
		59	- 02	1	_	_				\vdash	\vdash	 	 								00	15	00				1		1	_	\vdash	-	\vdash
θ51	81			- ^ ^	- ^ ^	^^	—	-	\vdash	_	\vdash	_	—				θ116	15			99	15	99				-	\vdash	<u> </u>	\vdash	\vdash	-	\vdash
θ52	80	60	80	60	80	60											θ117	13															$oldsymbol{\sqcup}$
θ53	80	61															θ118	12			99]	\Box
θ54	79	62	79	62													θ119	11															\Box
θ55	78	62															0120	10			100	10	100	10	100				1			-	-
		63	77	60	77	60	77	63			\vdash	 	 				θ121	9			100	, · · ·	100	-10	100		1		1	_	\vdash	-	\vdash
056	77		77	63	//	63	77	03	\vdash	\vdash	\vdash	Ь—	Ь—	—							400	\vdash		<u> </u>	<u> </u>	Ь—	-	—	-		\vdash		\vdash
θ57	77	64															θ122	7		7	100	oxdot					<u> </u>		L				ldot
θ58	76	65	76	65	L	L	L	L	L	L	L	L	L	L	L	L	θ123	6		L	L_			L	L	L	L	L	L	L			
θ59	75	66															θ124	5	100	5	100	5	100										\Box
060	74	67	74	67	74	67											θ125	4		ŕ	Ť	-							1			\neg	-
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θ62	72	69	72	69								Ь	Ь	L			θ127	1				oxdot					<u> </u>		└		$oxed{oxed}$		ш
θ63	72	70				Щ.											θ128	0	100	0	100	0	100	0	100	0	100	0	100	0	100	لـــــا	
θ64	71	71	71	71	71	71	71	71	71	71	71	71	71	71	100	100																	
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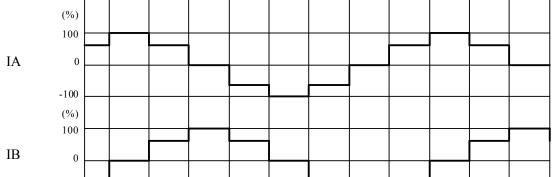
(15) Current wave example in each excitation mode (2 phase, 1-2 phase, W1-2 phase, 4W1-2 phase) 2 phase excitation (CW mode)



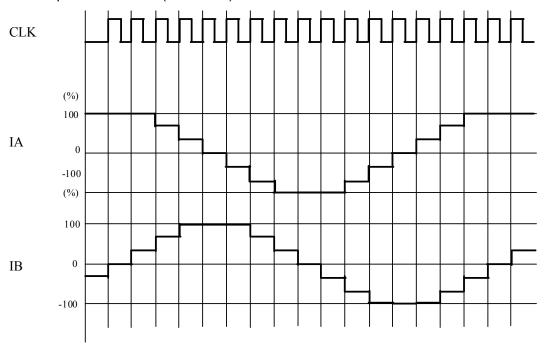


1-2 phase excitation (CW mode)

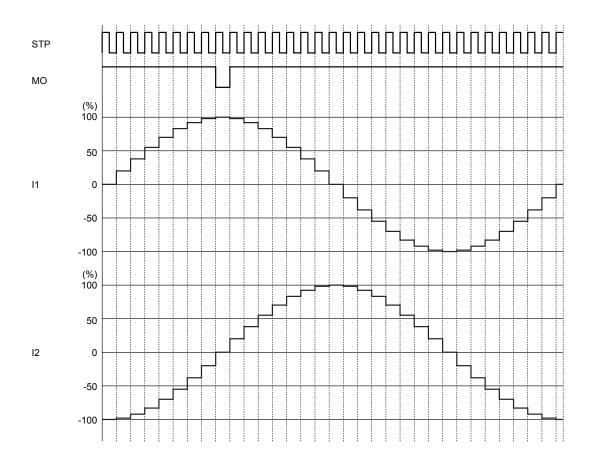
-100



W1-2 phase excitation (CW mode)



4W1-2 phase excitation (CW mode)

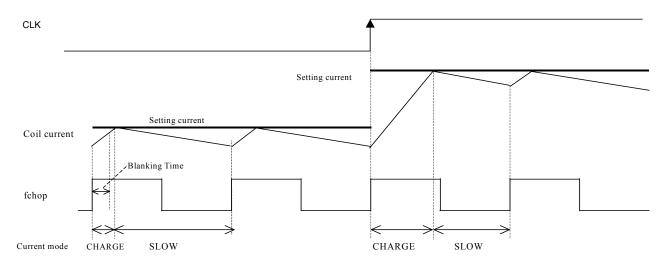


(16) Current control operation

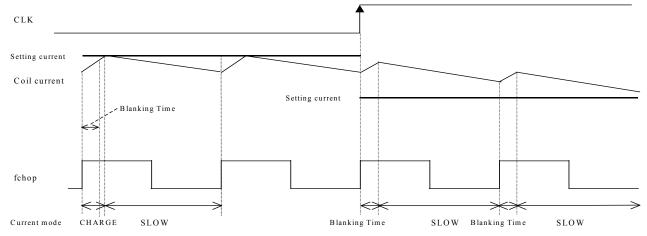
SLOW DECAY current control operation

When FDT pin voltage is a voltage over 3.5 V, the constant-current control is operated in SLOW DECAY mode.

(Sine-wave increasing direction)



(Sine-wave decreasing direction)



Each of current modes operates with the follow sequence.

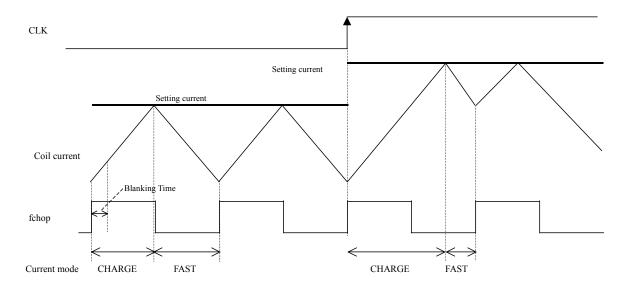
- The IC enters CHARGE mode at a rising edge of the chopping oscillation. (A period of CHARGE mode (Blanking Time) is forcibly present in approximately 1 µs, regardless of the current value of the coil current (ICOIL) and set current (IREF)).
- After the period of the blanking time, the IC operates in CHARGE mode until ICOIL ≥ IREF. After that, the mode switches to the SLOW DECAY mode and the coil current is attenuated until the end of a chopping period.

At the constant-current control in SLOW DECAY mode, following to the setting current from the coil current may take time (or not follow) for the current delay attenuation.

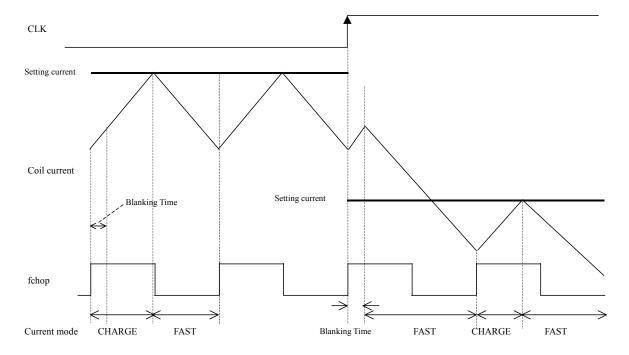
FAST DECAY current control operation

When FDT pin voltage is a voltage under 0.8V, the constant-current control is operated in FAST DECAY mode.

(Sine-wave increasing direction)



(Sine-wave decreasing direction)



Each of current modes operates with the follow sequence.

The IC enters CHARGE mode at a rising edge of the chopping oscillation.

(A period of CHARGE mode (Blanking Time) is forcibly present in approximately 1µs, regardless of the current value of the coil current (ICOIL) and set current (IREF)).

After the period of the blanking time, The IC operates in CHARGE mode until ICOIL \geq IREF. After that, the mode switches to the FAST DECAY mode and the coil current is attenuated until the end of a chopping period. At the constant-current control in FAST DECAY mode, following to the setting current from the coil current takes short-time for the current fast attenuation, but, the current ripple value may be higher.

MIXED DECAY current control operation

(Sine-wave increasing direction) CLK Setting current Coil current Fichop

CHARGE

SLOW

FAST

CLK Setting current Coil current Setting current Setting current Blanking Time Setting current Blanking Time FAST CHARGE SLOW FAST Blanking Time FAST CHARGE SLOW

Each of current modes operates with the follow sequence.

SLOW

CHARGE

Current mode

FAST

The IC enters CHARGE mode at a rising edge of the chopping oscillation.

(A period of CHARGE mode (Blanking Time) is forcibly present in approximately 1 μ s, regardless of the current value of the coil current (ICOIL) and set current (IREF)).

In a period of Blanking Time, the coil current (ICOIL) and the setting current (IREF) are compared.

If an ICOIL = IREF state exists during the charge period:

The IC operates in CHAGE mode until ICOIL \geq IREF. After that, it switches to SLOW DECAY mode and then switches to FAST DECAY mode in the last approximately 1 μ s of the period.

If no ICOIL = IREF state exists during the charge period:

The IC switches to FAST DECAY mode and the coil current is attenuated with the FAST DECAY operation until the end of a chopping period.

The above operation is repeated.

Normally, in the sine wave increasing direction the IC operates in SLOW (+FAST) DECAY mode, and in the sine wave decreasing direction the IC operates in FAST DECAY mode until the current is attenuated and reaches the set value and the IC operates in SLOW (+FAST) DECAY mode.

Power Dissipation

Power dissipation calculation of STK682-010-E following becomes.

2-phase excitation

 $Pd=IOH\times(Ronu+Rond)^2$

1-2-phase excitation

 $Pd=0.71\times IOH\times (Ronu + Rond)^2$

Please by substituting from electrical characteristic table value of Rond and Ronu.

Thermal design

[Operating range in which a heat sink is not used]

Use of a heat sink to lower the operating substrate temperature of the HIC (Hybrid IC) is effective in increasing the quality of the HIC.

The size of heat sink for the HIC varies depending on the magnitude of the average power loss, PdAV, within the HIC. The value of PdAV increases as the output current increases. To calculate PdAV, refer to "Calculating Internal HIC Loss for the STK672-640C-E in the specification document.

Calculate the internal HIC loss, PdAV, assuming repeat operation such as shown in Figure 1 below, since conduction during motor rotation and off time both exist during actual motor operations,



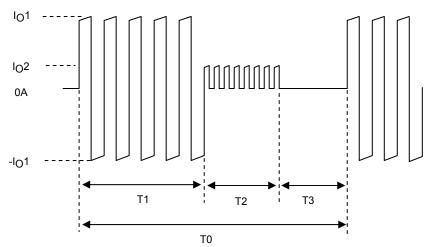


Figure 1 Motor Current Timing

T1: Motor rotation operation time

T2: Motor hold operation time

T3: Motor current off time

T2 may be reduced, depending on the application.

T0: Single repeated motor operating cycle

IO1 and IO2: Motor current peak values

Due to the structure of motor windings, the phase current is a positive and negative current with a pulse form.

Note that figure 1 presents the concepts here, and that the on/off duty of the actual signals will differ.

The hybrid IC internal average power dissipation PdAV can be calculated from the following formula.

$$PdAV = (T1 \times P1 + T2 \times P2 + T3 \times 0) \cdot TO ---- (I)$$

(Here, P1 is the PdAV for IO1 and P2 is the PdAV for IO2)

If the value calculated using Equation (I) is 1.5W or less, and the ambient temperature, Ta, is 60°C or less, there is no need to attach a heat sink. Refer to Figure 2 for operating substrate temperature data when no heat sink is used.

[Operating range in which a heat sink is used]

Although a heat sink is attached to lower Tc if PdAV increases, the resulting size can be found using the value of c-a in Equation (II) below and the graph depicted in Figure 3.

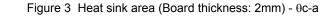
$$c-a = (Tc max-Ta) \cdot PdAV ---- (II)$$

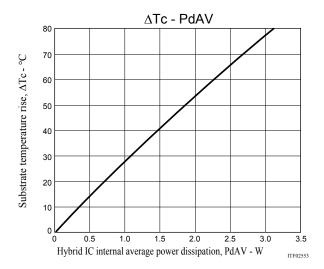
Tc max: Maximum operating substrate temperature =105°C

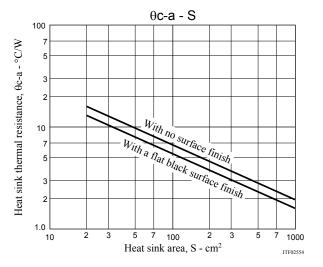
Ta: HIC ambient temperature

Although a heat sink can be designed based on equations (I) and (II) above, be sure to mount the HIC in a set and confirm that the substrate temperature, Tc, is 105°C or less.

Figure 2 Substrate temperature rise, ΔTc (no heat sink) - Internal average power dissipation, PdAV

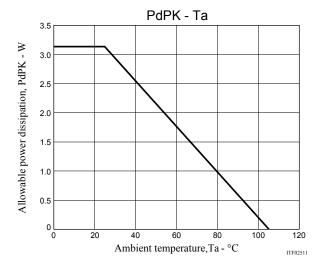






Mitigated Curve of Package Power Loss, PdPK, vs. Ambient Temperature, Ta Package power loss, PdPK, refers to the average internal power loss, PdAV, allowable without a heat sink. The figure below represents the allowable power loss, PdPK, vs. fluctuations in the ambient temperature, Ta. Power loss of up to 3.1W is allowable at Ta=25°C, and of up to 1.75W at Ta=60°C.

Allowable power dissipation, PdPK(no heat sink) - Ambient temperature, Ta



ORDERING INFORMATION

Device	Package	Shipping (Qty / Packing)
STK682-010-E	SIP-19 (Pb-Free)	15 / Tube

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